



S₁V

1.0A SURFACE MOUNT GLASS PASSIVATED RECTIFIER

Features

- Glass Passivated Die Construction for High Reliability
- Low Forward Voltage Drop
- Surge Overload Rating to 30A Peak
- Ideally Suited for Automated Assembly
- Very High Reverse Breakdown Voltage
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: SMA
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead-Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 (3)
- Polarity: Cathode Band or Cathode Notch
- Weight: 0.064 grams (Approximate)





Top View

Bottom View

Ordering Information (Note 4)

| Part Number | Qualification | Case | Packaging |
|-------------|---------------|------|-------------------|
| S1V-13-F | Commercial | SMA | 5,000/Tape & Reel |

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information





Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

| Characteristic | Symbol | Value | Unit |
|---|--|-------|--------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V _{RRM} V _{RWM} V _R | 2,000 | V |
| RMS Reverse Voltage | V _{R(RMS)} | 1400 | V |
| Average Rectified Output Current @ $T_T = +100$ °C | lo | 1.0 | Α |
| Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load | I _{FSM} | 30 | Α |
| I ² t Rating for Fusing (t < 8.3ms) | l ² t | 3.74 | A^2S |

Thermal Characteristics

| Characteristic | Symbol | Value | Unit |
|--|------------------|-------------|------|
| Typical Thermal Resistance, Junction to Ambient (Note 5) | R _{0JA} | 50 | °C/W |
| Operating and Storage Temperature Range | $T_{J_1}T_{STG}$ | -55 to +150 | °C |

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | | Symbol | Min | Тур | Max | Unit |
|------------------------------------|--------------------------|--------------------|-------|-----|-----|------|
| Reverse Breakdown Voltage(Note 7) | @ $I_R = 5\mu A$ | V _{(BR)R} | 2,000 | _ | _ | V |
| Forward Voltage | @ I _F = 1.0A | VF | _ | 1.0 | 1.3 | V |
| Peak Reverse Leakage Current | @ T _A = +25°C | | _ | 0.2 | 5.0 | |
| at Rated DC Blocking Voltage | @ $T_A = +125$ °C | IR | _ | 37 | 100 | μΑ |
| Typical Total Capacitance (Note 6) | | C _T | _ | 4 | _ | pF |

Notes:

- 5. Thermal resistance junction to ambient at 0.375 inch (9.5mm) lead length.6. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.7. Short duration pulse test used to minimize self-heating effect.



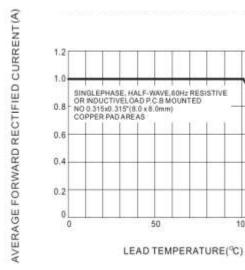
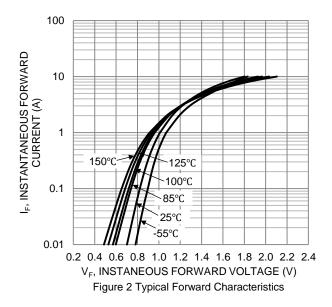


Figure 1 Maximum Average Forward Current Derating

100

150



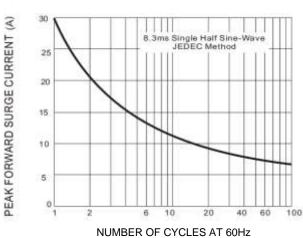
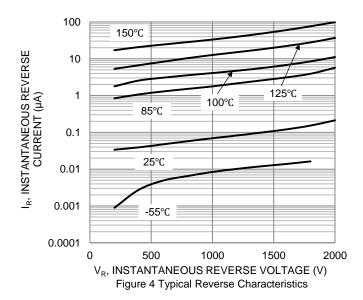
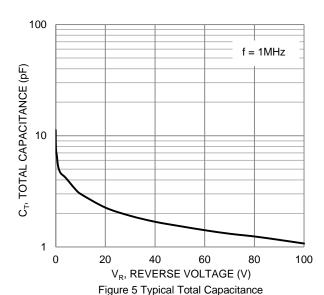


Figure 3 Maximum Non-Repetitive Surge Current



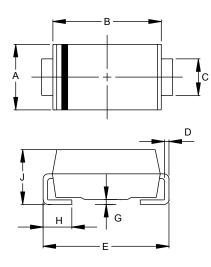




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SMA

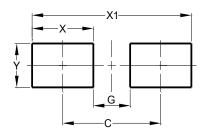


| SMA | | | | |
|----------------------|------|------|--|--|
| Dim | Min | Max | | |
| Α | 2.29 | 2.92 | | |
| В | 4.00 | 4.60 | | |
| C | 1.27 | 1.63 | | |
| D | 0.15 | 0.31 | | |
| Е | 4.80 | 5.59 | | |
| G | 0.05 | 0.20 | | |
| Н | 0.76 | 1.52 | | |
| 7 | 1.96 | 2.40 | | |
| All Dimensions in mm | | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SMA



| Dimensions | Value (in mm) |
|------------|------------------|
| С | 4.00 |
| G | 1.50 |
| X | 2.50 |
| X1 | 6.50 |
| Υ | 1.70 |

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.



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